

CLAIMS

1. A pressure-sensitive adhesive sheet comprising a base material and a pressure-sensitive adhesive layer, having formed therein a plurality of through holes passing through from one surface to the other surface thereof, and being exposed at maximum temperature T_{max} (wherein $20^{\circ}\text{C} \leq T_{max} \leq 130^{\circ}\text{C}$) after having been stuck onto an adherend, the pressure-sensitive adhesive sheet characterized in that:

said through holes have a diameter in said base material and said pressure-sensitive adhesive layer in a range of 0.1 to 300 μm , and a hole density in a range of 30 to 50,000 per 100 cm^2 ;

and said pressure-sensitive adhesive layer has a storage modulus at T_{max} of not less than $4.5 \times 10^3 \text{ Pa}$, and a loss tangent at T_{max} of not more than 0.78.

2. A pressure-sensitive adhesive sheet comprising a base material and a pressure-sensitive adhesive layer, and having formed therein a plurality of through holes passing through from one surface to the other surface thereof, the pressure-sensitive adhesive sheet characterized in that:

said through holes have a diameter in said base material and said pressure-sensitive adhesive layer in a range of 0.1 to 300 μm , and a hole density in a range of 30 to 50,000 per 100 cm^2 ;

and said pressure-sensitive adhesive layer has a storage modulus at 120°C of not less than $4.5 \times 10^3 \text{ Pa}$, and a loss tangent

at 120 °C of not more than 0.78.

3. The pressure-sensitive adhesive sheet according to claim 1 or 2, characterized in that said through holes are formed by laser processing.